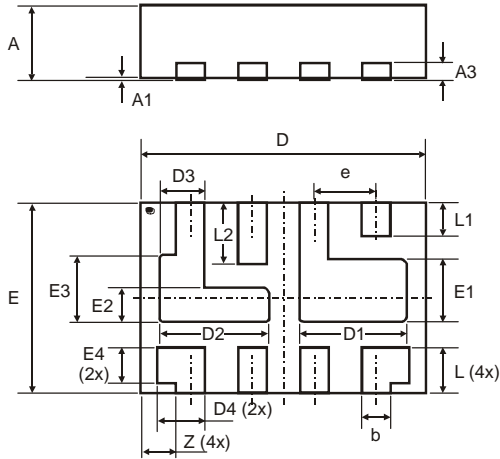


Package Outline Dimensions

W-DFN3020-8 (Type K)

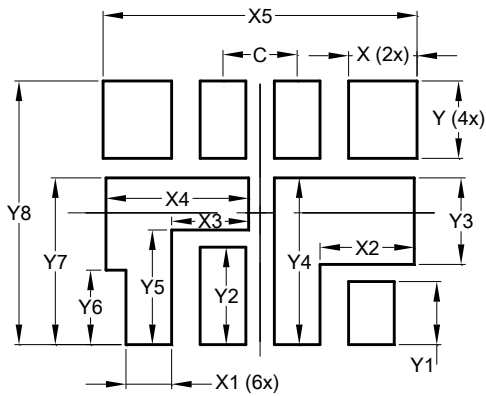


W-DFN3020-8 Type K							
Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.77	0.83	0.80	E1	0.56	0.76	0.66
A1	0.00	0.05	0.02	E2	0.26	0.46	0.36
A3	-	-	0.15	E3	0.605	0.805	0.705
b	0.25	0.35	0.30	E4	0.275	0.475	0.375
D	2.95	3.05	3.00	L	0.425	0.525	0.475
D1	1.025	1.225	1.125	L1	0.30	0.40	0.35
D2	1.05	1.25	1.15	L2	0.60	0.70	0.65
D3	0.375	0.575	0.475	Z	-	-	0.375
D4	0.40	0.60	0.50	e	-	-	0.65
E	1.95	2.05	2.00				

All Dimensions in mm

Suggested Pad Layout

W-DFN3020-8 (Type K)



Dimensions	Value (in mm)
C	0.650
X	0.600
X1	0.400
X2	0.825
X3	0.675
X4	1.250
X5	2.750
Y	0.675
Y1	0.550
Y2	0.850
Y3	0.755
Y4	1.455
Y5	1.000
Y6	0.650
Y7	1.455
Y8	2.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.